

Radiation-Hard Optical Link in the ATLAS Pixel Detector

K.K. Gan

The Ohio State University

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K.E. Arms, K.K. Gan, M. Johnson, H. Kagan, R. Kass, A. Rahimi,
C. Rush, S. Smith, R. Ter-Antonian, M.M. Zoeller
The Ohio State University

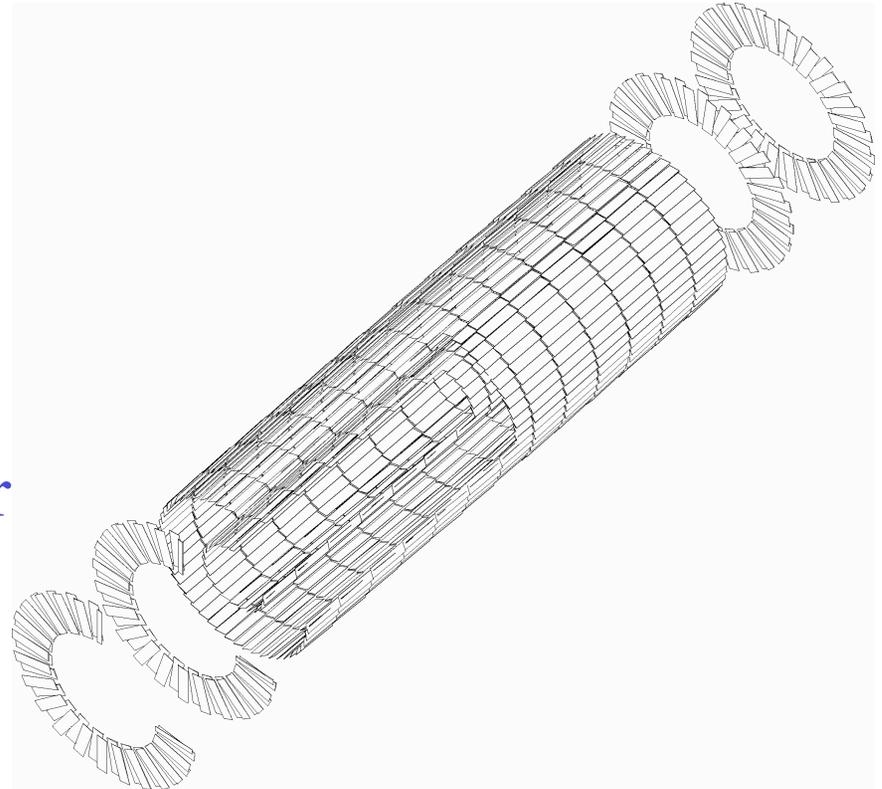
A. Ciliox, M. Holder, S. Nderitu, M. Ziolkowski
Universitaet Siegen, Germany

Outline

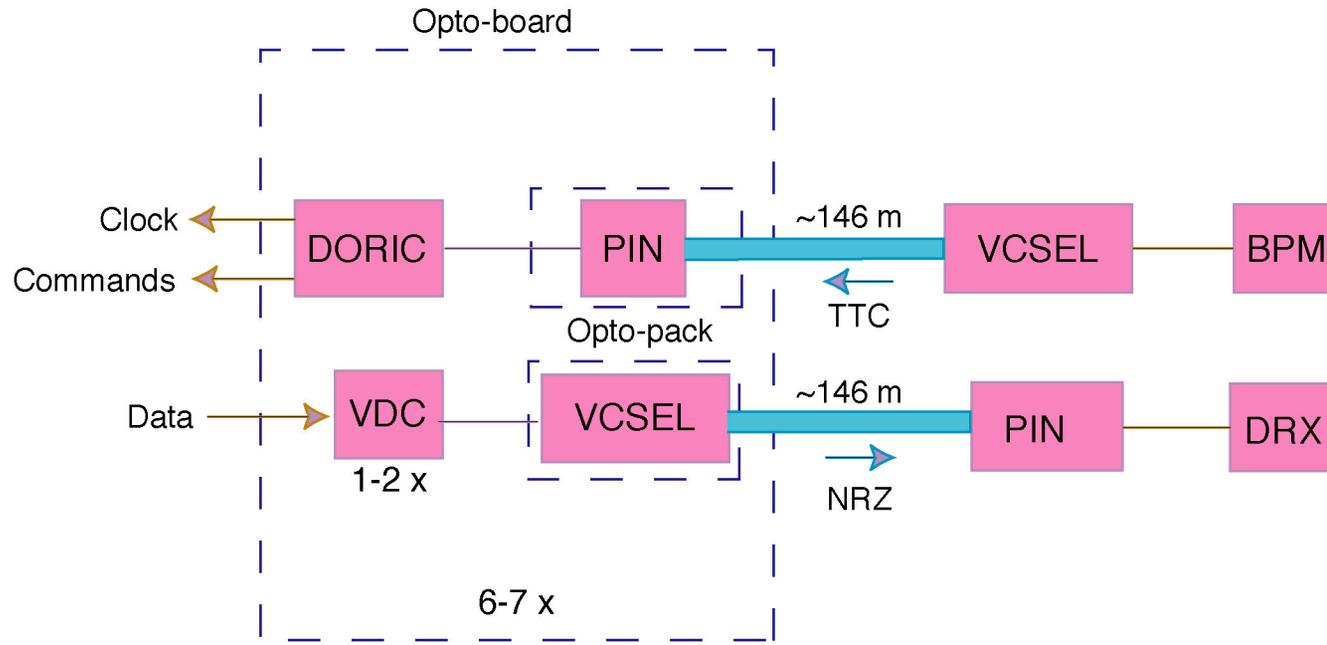
- Introduction
- Results on IBM 0.25 μ m Chips
- Results on Proton Irradiations
- Summary

ATLAS Pixel Detector

- Inner most tracking detector
- Pixel size: $50 \mu\text{m} \times 400 \mu\text{m}$
- 100 million channels
- Barrel layers at $r = 5.1, 12.3 \text{ cm}$
- Disks at $z = 50, 65 \text{ cm}$
- Dosage after 10 years:
 - ◆ optical link: 30 Mrad or $6 \times 10^{14} \text{ 1-MeV } n_{\text{eq}}/\text{cm}^2$



ATLAS Pixel Opto-link



VCSEL: Vertical Cavity Surface Emitting Laser diode

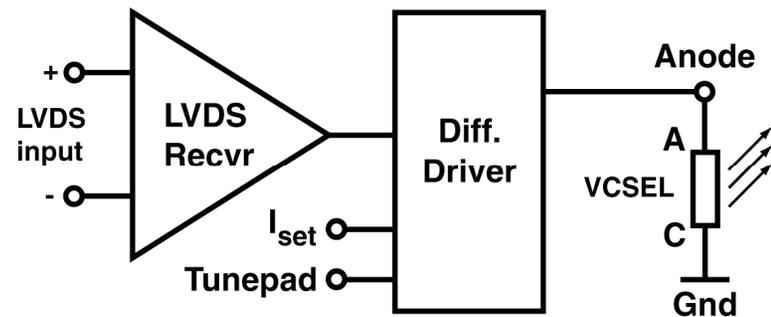
VDC: VCSEL Driver Circuit

PIN: PiN diode

DORIC: Digital Optical Receiver Integrated Circuit

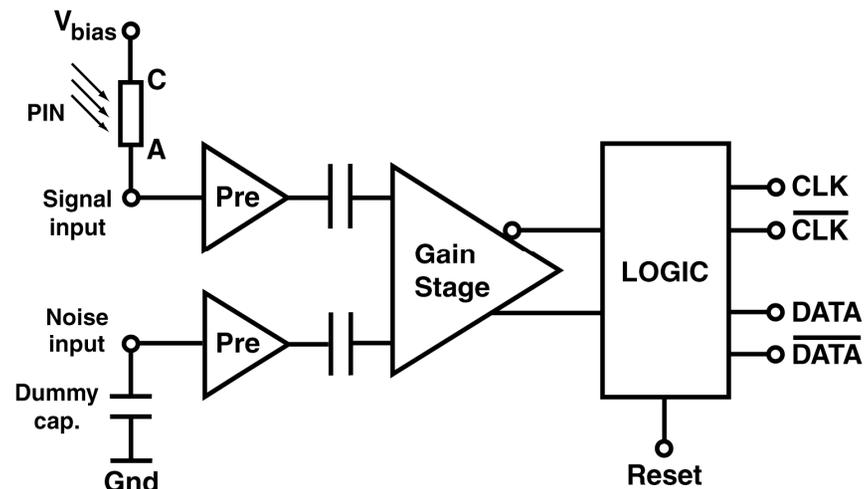
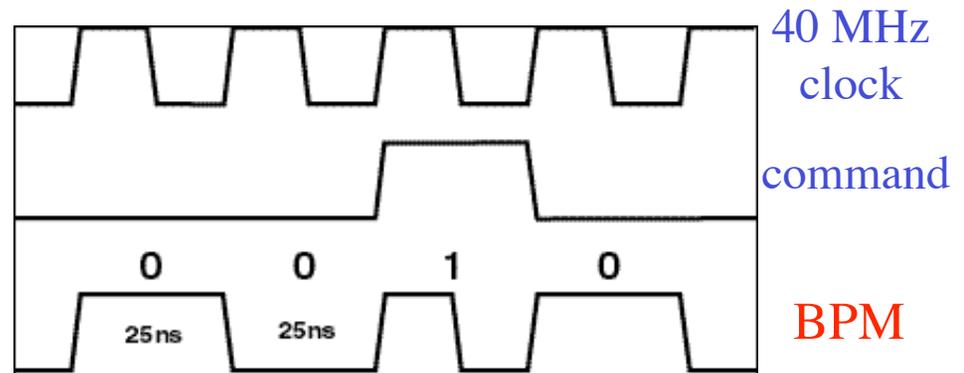
VDC: VCSEL Driver Circuit

- Convert LVDS input signal into single-ended signal appropriate to drive VCSEL diode
- Output (bright) current: 0 to 20 mA
 - ◆ controlled by external current I_{set}
- Standing (dim) current: ~ 1 mA
 - ◆ improve switching speed
- Rise & fall times: 1 ns nominal for 40 MHz signals
- “On” voltage of VCSEL: up to 2.3 V at 20 mA for 2.5 V supply
- Constant current consumption!
- Use Truelight high-power oxide common cathode VCSEL array



DORIC: Digital Optical Receiver IC

- Decode Bi-Phase Mark encoded (BPM) clock and command signals from PIN diode
- Input signal: 40-1000 μA
- Extract: 40 MHz clock
- Duty cycle: $(50 \pm 4)\%$
- Total timing error: $< 1 \text{ ns}$
- Bit Error Rate (BER): $< 10^{-11}$ at end of life
- Use Truelight common cathode PIN array

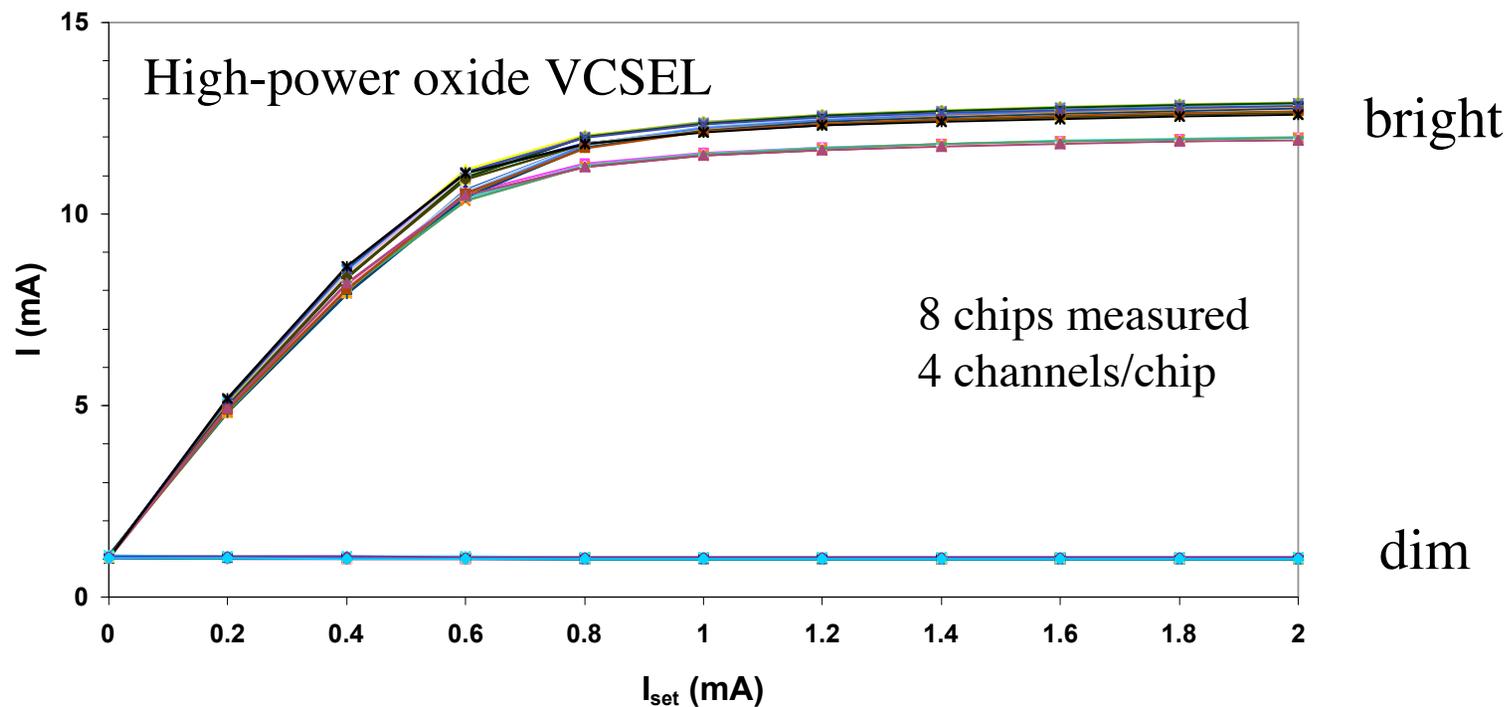


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Status of VDC & DORIC

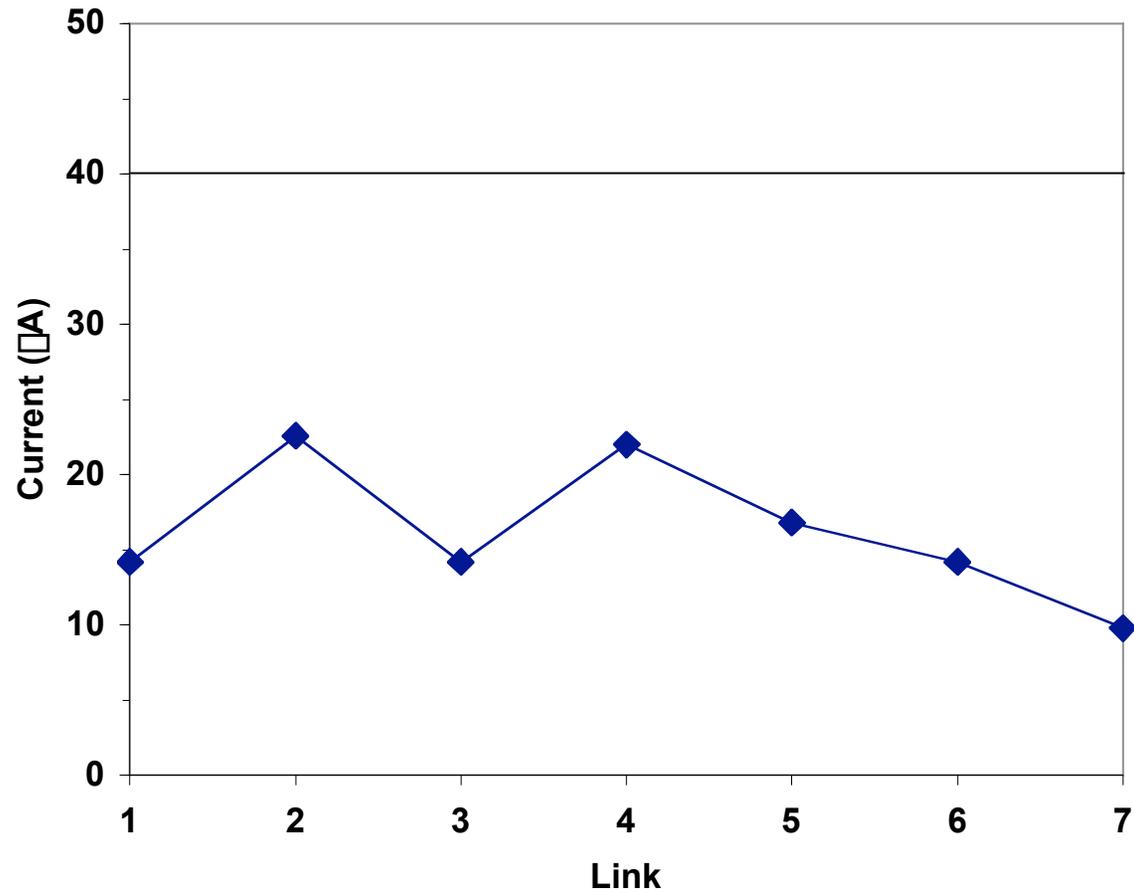
- Original design for ATLAS SemiConductor Tracker (SCT)
 - AMS 0.8 μ m BiPolar in radiation tolerant process (4 V)
- DMILL #1-3: Summer 1999 - May 2001
 - 0.8 μ m CMOS rad-hard process (3.2 V)
 - VDC & DORIC #3: meet specs
 - severe degradation of circuit performance in April 2001 proton irradiation
- IBM #1-5: Summer 2001 - Dec 2002
 - 0.25 μ m CMOS rad-hard process (2.5 V)
 - enclosed layout transistors and guard rings for improved radiation hardness
- IBM 5e: April 2003 engineering run
 - convert 3-layer to 5-layer layout for submission with pixel Module Control Chip (MCC) for cost saving
 - ⇒ this is the production run since chips meet specs and sufficient quantity of chips were produced

VDC-I5e: Bright and Dim Currents vs. I_{set}



- dim current is ~ 1 mA as expected
- bright current measured with $1 \square$ in series
- maximum bright current is ~ 13 mA
 - ◆ oxide VCSEL has larger effective resistance than p^+ implanted VCSEL
 - ◆ target is 20 mA but 13 mA is adequate for annealing from irradiation damage

DORIC: PIN Current Thresholds with No Bit Errors

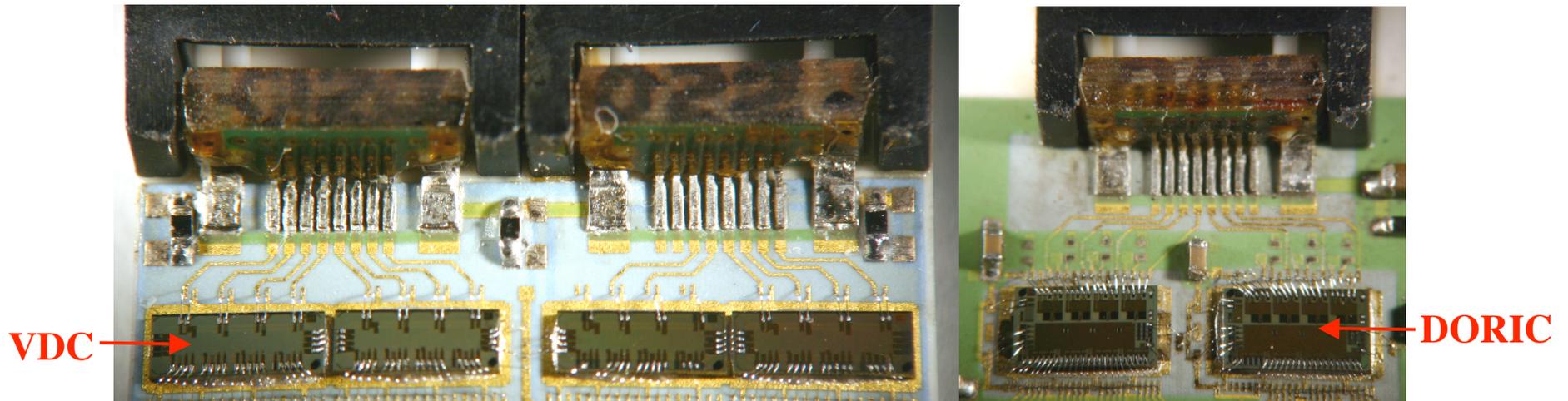
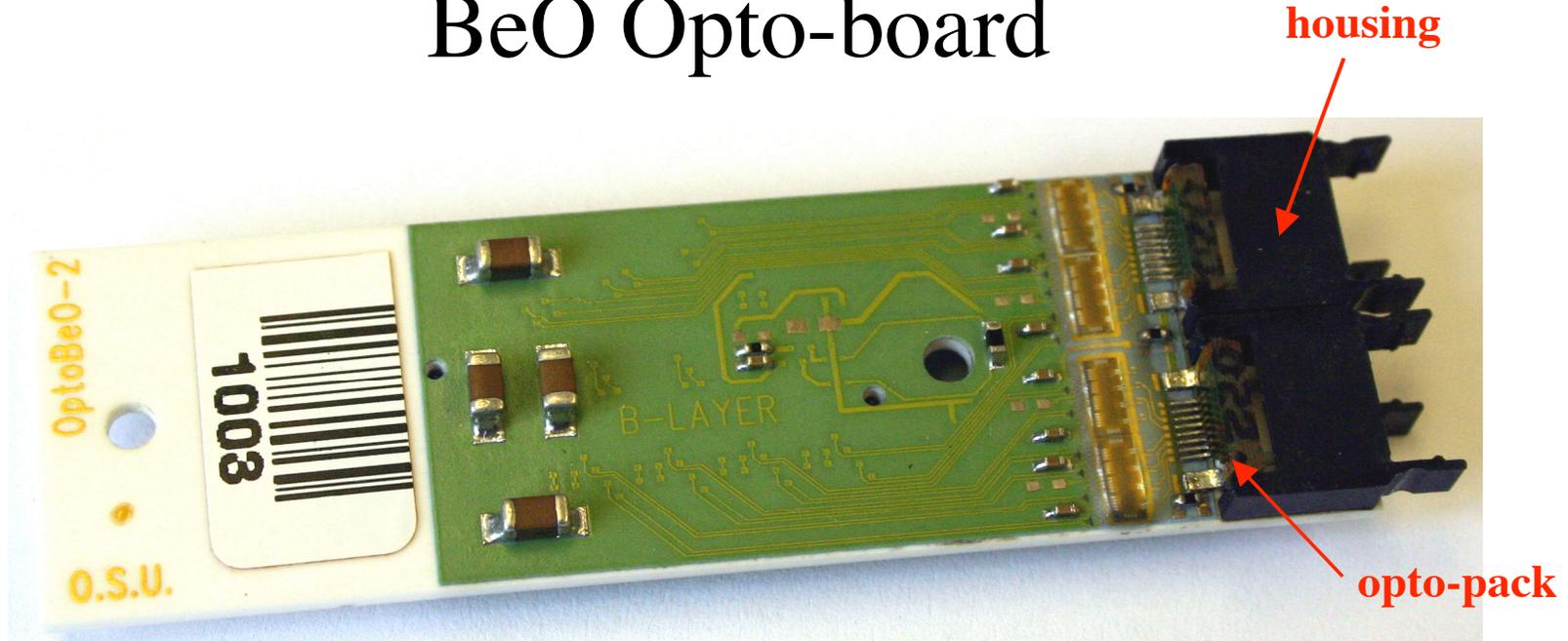


● thresholds significantly better than spec: 40 µA

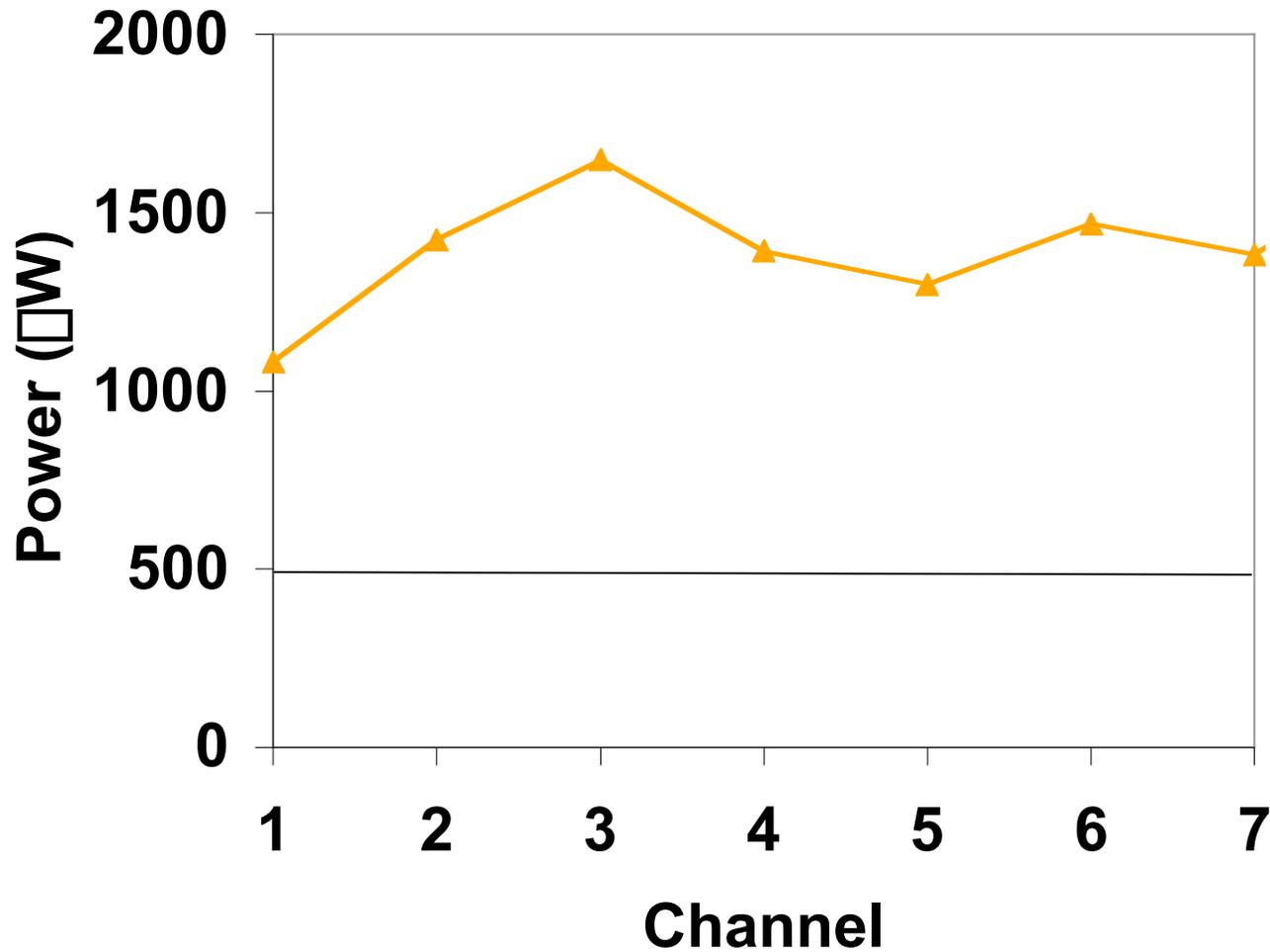
Status of BeO Opto-board

- converts: optical signal ↔ electrical signal
- contains 7 optical links
- use BeO for heat management but prototype initially in FR-4 for fast turnaround and cost saving
- 1st BeO prototype:
 - ◆ many open vias due to insufficient gold filling
 - ✓ opto-links works after via repairs!
- 2nd BeO prototype:
 - ◆ recycled BeO boards
 - ◆ many shorts due to over filling
 - ⇒ use more experienced/expensive vendor
 - ⇒ produced opto-boards of high quality

BeO Opto-board



Optical Power

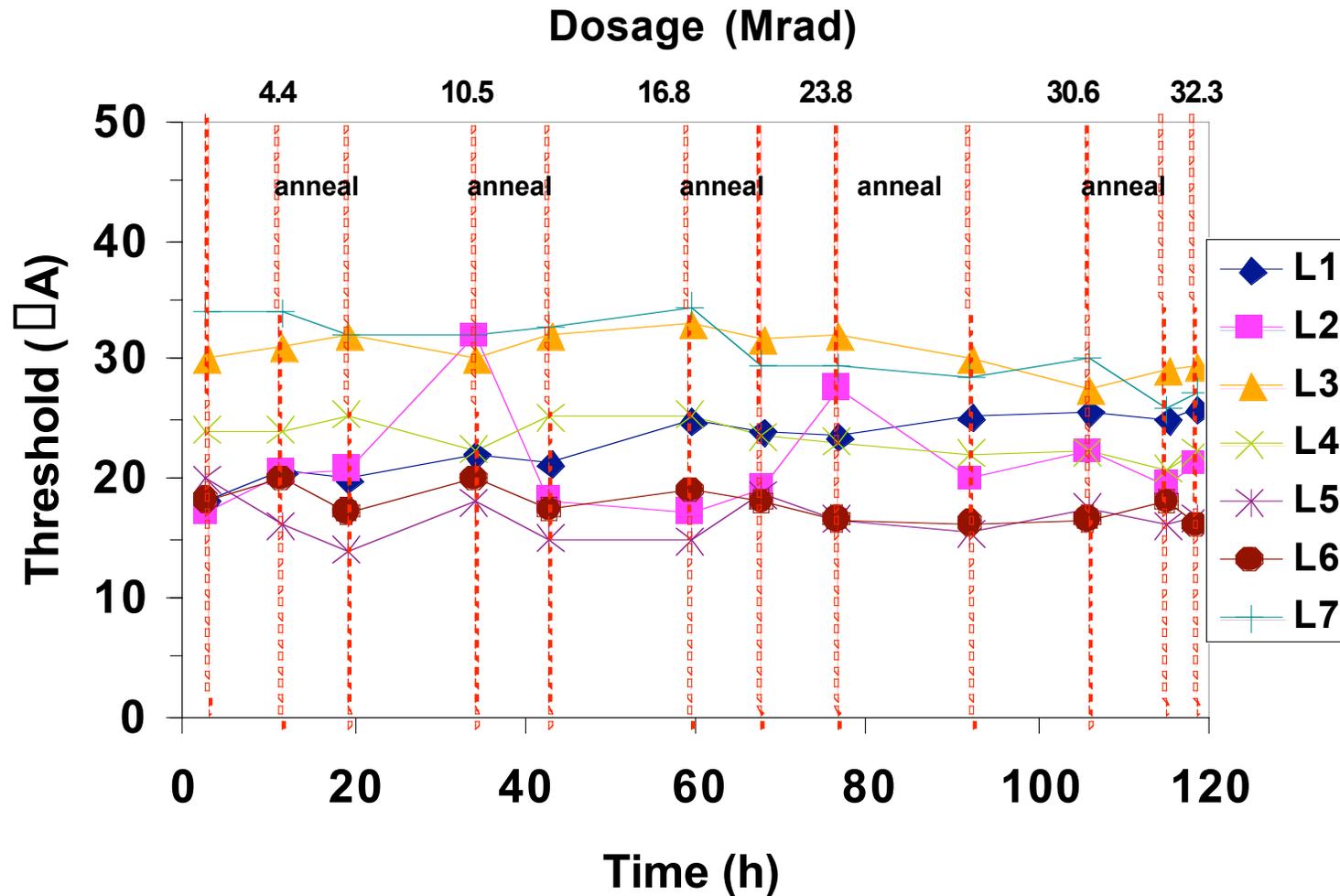


- optical power at 10 mA significantly above spec: 500 μW

Opto-board Status

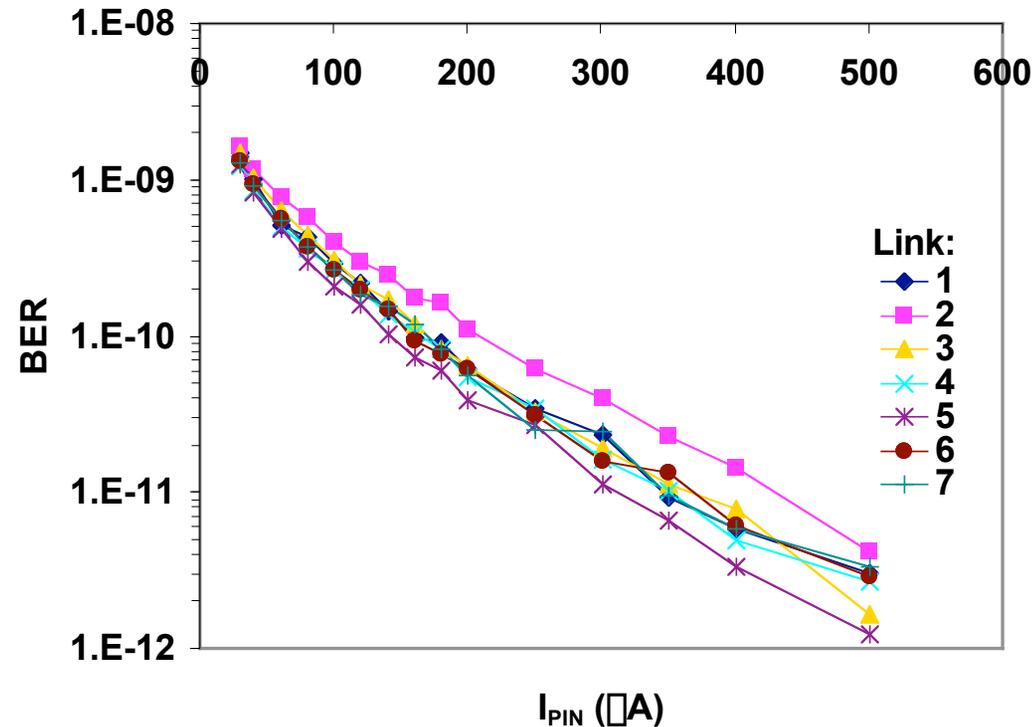
- 28 boards were delivered
 - ◆ ~equal mixture of boards for layers B and 1, 2, disk
 - ◆ populated opto-boards have low noise and good optical power
 - ⇒ no known circuit design errors
 - ◆ a few SMD detached from three boards
 - ⇒ produce 80 B-layer boards with layout changes to improve adhesion
 - ⇒ expected delivery in September
 - if new boards are satisfactory
 - ⇒ produce 430 boards for layers 1, 2, and disk

PIN Current Threshold vs Dosage



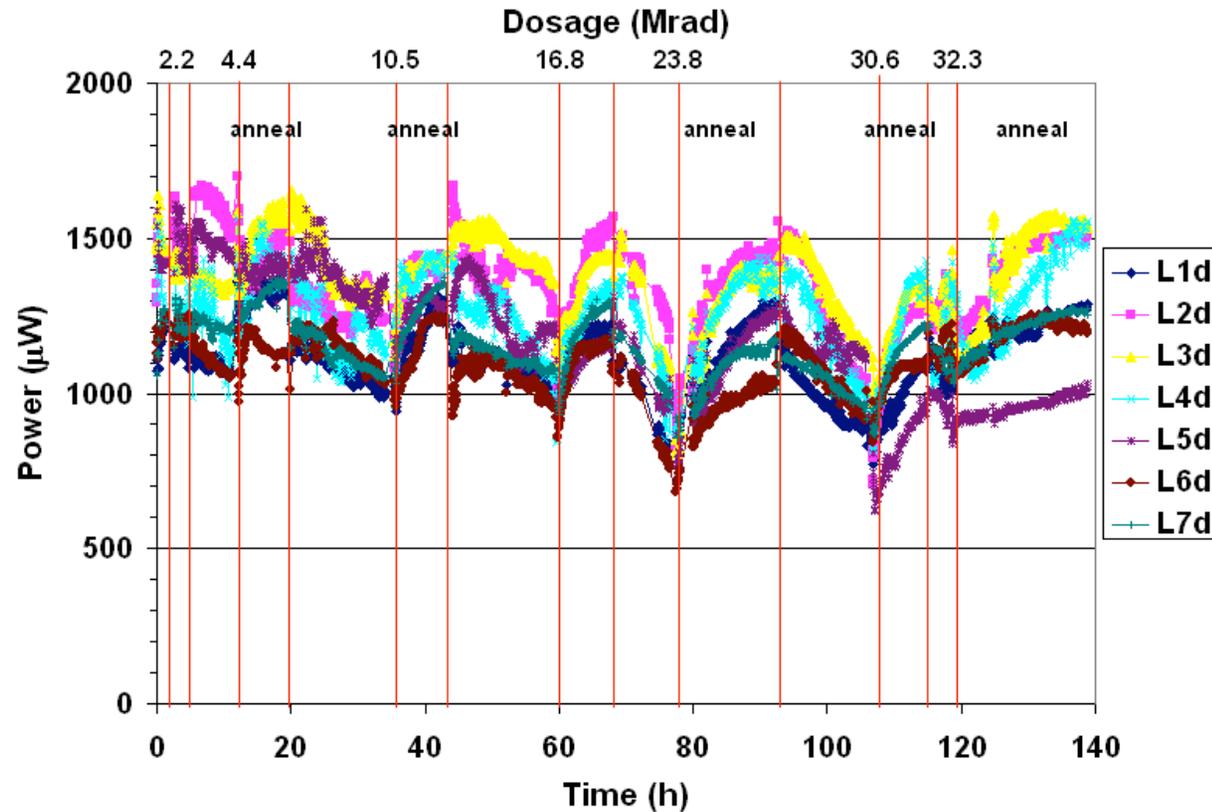
Proton Induced Bit Errors in PIN

- convert observed bit errors into bit error rate at opto-link location:



- bit error rate decreases with increasing PIN current as expected
- bit error rate $\sim 3 \times 10^{-10}$ at 100 μA (1.4 errors/minute)
- DORIC spec: 10^{-11}

Optical Power vs Dosage



- irradiation procedure: ~ 5 Mrad/day (10 hours) with the rest of day annealing
- optical power decreases with dosage as expected
- limited annealing recovers some lost power
- still have good optical power after 30 Mrad

Summary

- VDC-I5e & DORIC-I5e (IBM 0.25 μ m):
 - ✓ radiation hard up to 62 Mrad
 - ✓ meet ATLAS pixel specs
 - ✓ production is completed
- BeO opto-board:
 - ✓ several pre-production opto-boards have been fabricated
 - low PIN current thresholds for no bit errors
 - excellent optical power
 - ✓ radiation hard up to \sim 30 Mrad
 - modify layout to improve SMD adhesion
- start opto-link production in September 2004
 - complete production by September 2005